

The 10th International Conference on Integrated Circuits and Microsystems

October 17-19, 2025 | Hefei, China

www.icicm.net

2025 The 10th International Conference on Integrated Circuits and Microsystems (ICICM 2025) will be held in Hefei, China on October 17-19, 2025, which is co-sponsored by Anhui University; Southeast University and University of Electronic Science and Technology of China.

10th ICICM 2025

Invited Speakers Recruitment

- ICICM 2025 recruit domestic and international invited speakers in the Integrated Circuits and Microsystems field.
- ICICM 2025 will assign the selected presentations to relevant forums. Applicants are requested to send their resumes, academic achievements, speech title and abstract, and two-inch photo as attachments to icicm_conf@vip.163.com.
- Invited speakers are required to share best practices and research results, and are not allowed to promote any products or services during the speech.

Topics

Include but not limited

- **Track 1: Electronic Design Automation (EDA)**
 - Progress of EDA algorithms
 - EDA for emerging technologies
 - Hardware-software co-design with EDA
 - EDA in High Performance Computing (HPC)
 - EDA in analog and mixed-signal design
- **Track 2: Integrated Circuit and System Design**
 - Digital, analog, mixed-signal IC and SOC design technology
 - IC computer-aided design technology, DFM
 - Modeling and simulation
- **Track 3: Semiconductor Devices and Circuits**
 - Components and circuits for wireless systems
 - Low power, RF devices and circuits
 - Silicon/Germanium Devices and Device Physics
 - Compound semiconductor devices and circuits
- **Track 4: Process Technology and Manufacturing**
 - Silicon integrated circuits and manufacturing
 - Interconnect, low-K, high-K and other process technologies
 - Packaging and testing technology, equipment technology

For more topics, please visit at: <http://icicm.net/call-for-papers.html>

Track Recruitment

If you are willing to organize one or more tracks, please contact us to get more details. All papers in track will also be included in the conference proceedings and indexed by EI Compendex and Scopus.

Submission

1. Full paper (Presentation & Publication)
2. Abstract (Presentation only)

Submission Link:

<https://easychair.org/conferences/?conf=icicm2025>

Email submission: icicm_conf@vip.163.com

Full paper template (Word): <http://icicm.net/files/Template.doc>

Full paper template (Latex):

<http://icicm.net/files/IEEE-conference-proceeding-Latex.rar>

Publication

Submitted papers will be Peer-Reviewed (Double Blind) and the accepted ones will be collected in the conference proceedings and indexed by EI Compendex and Scopus, etc.

**Proceedings of ICICM2016-2024 have been successfully include in IEEE Xplore and indexed by EI Compendex and Scopus already!

Conference History

ICICM2016	Chengdu	IEEE	ISBN: 978-1-5090-2814-6
ICICM2017	Nanjing	IEEE	ISBN: 978-1-5386-3506-3
ICICM2018	Shanghai	IEEE	ISBN: 978-1-5386-8311-8
ICICM2019	Beijing	IEEE	ISBN: 978-1-7281-5132-8
ICICM2020	Nanjing	IEEE	ISBN: 978-1-7281-8978-9
ICICM2021	Nanjing	IEEE	ISBN: 978-1-6654-5886-3
ICICM2022	Xi'an	IEEE	ISBN: 978-1-6654-6042-2
ICICM2023	Nanjing	IEEE	ISBN: 979-8-3503-1849-4
ICICM2024	Wuhan	IEEE	ISBN: 979-8-3315-0944-6

Important Dates

Submission Deadline	Notification Deadline	Registration Deadline
July 15, 2025	August 10, 2025	August 25, 2025

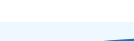
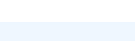
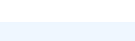
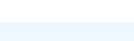
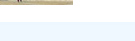
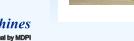
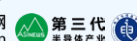
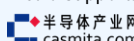
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Venue



Wendian Pavilion Library
(Qingyuan Campus, Anhui University)